

Z-PACK | Z-PACK 2mm HM

TE Internal #: 106081-1

Hard Metric Backplane PCB Mount Header, ≤1 Gb/s, 11 Column, 7 Row, Mezzanine, 77 Position, 2 mm [.078 in] Centerline, Vertical,

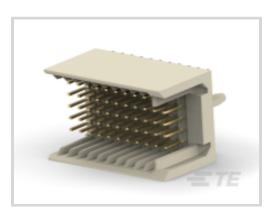
Gray, Z-PACK 2mm HM

View on TE.com >



Connectors > PCB Connectors > Backplane Connectors > Hard Metric Backplane Connectors >

Hard Metric Male Connector: Traditional Backplane, Mezzanine, 2mm











PCB Connector Type: PCB Mount Header

Data Rate: ≤1 Gb/s

Number of Columns: 11

Number of Rows: 7

Backplane Architecture: Mezzanine

All Hard Metric Male Connector: Traditional Backplane, Mezzanine, 2mm (124)

Features

Product Type Features

Connector & Contact Terminates To	Printed Circuit Board
Ground Feature Type	Ground Return Shielding
Backplane Interface Type	2mm HM
Connector System	Board-to-Board
PCB Connector Type	PCB Mount Header
Sealable	No

Configuration Features

Rows Loaded	A, B, C, D, E, F, Z
Number of Columns	11
Number of Rows	7
Backplane Architecture	Mezzanine
Number of Positions	77



Signal Characteristics Crosstalk Version Standard Data Rate ≤1 Gb/s Body Features Primary Product Color Gray Contact Features Contact Underplating Material Nickel Contact Base Material Phosphor Bronze CompactPCI Designation None PCB Contact Termination Area Plating Material Tin-Lead Feedthrough Post Length 3.7 mm Contact Type Pin Contact Mating Area Plating Material Gold (Au) Contact Mating Area Plating Material Thickness .76 μm[30 μin] Contact Current Rating (Max) 1.5 A
Data Rate Body Features Primary Product Color Contact Features Contact Underplating Material Contact Base Material CompactPCI Designation PCB Contact Termination Area Plating Material Feedthrough Post Length Contact Type Contact Mating Area Plating Material Contact Mating Area Plating Material Find Gold (Au) Contact Mating Area Plating Material Thickness ≥1 Gb/s All Gb/s Fragery Fragery
Primary Product Color Gray Contact Features Contact Underplating Material Nickel Contact Base Material Phosphor Bronze CompactPCI Designation None PCB Contact Termination Area Plating Material Tin-Lead Feedthrough Post Length 3.7 mm Contact Type Pin Contact Mating Area Plating Material Gold (Au) Contact Mating Area Plating Material Thickness .76 µm[30 µin]
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Contact Mating Area Plating Material Contact Mating Area Plating Material Thickness .76 µm[30 µin]
Contact Mating Area Plating Material Thickness .76 µm[30 µin]
Contact Current Pating (May)
Contact Current Rating (Max) 1.5 A
Termination Features
Termination Method to PCB Through Hole - Press-Fit
Mechanical Attachment
Connector Mounting Type Board Mount
Mating Alignment Type Polarizing Peg
Front Mating Level Level 1
Housing Features
Housing Material Polyester - GF
Centerline (Pitch) 2 mm[.078 in]
Dimensions
Backplane Module Length 25 mm
Usage Conditions
Operating Temperature Range -55 – 125 °C[-67 – 257 °F]
Operation/Application
Shielded



Circuit Application	Signal
Industry Standards	
UL Flammability Rating	UL 94V-0
Packaging Features	
Packaging Quantity	21
Packaging Method	Tube

Product Compliance

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Not Compliant
EU ELV Directive 2000/53/EC	Compliant with Exemptions
China RoHS 2 Directive MIIT Order No 32, 2016	Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JAN 2025 (247) Candidate List Declared Against: JAN 2025 (247) SVHC > Threshold: Pb (13% in 4690948374) Article Safe Usage Statements: Do not eat, drink or smoke when using this product. Wash thoroughly after handling. Recycle if possible and dispose of the article by following all applicable governmental regulations relevant to your geographic location.
Halogen Content	Not Low Halogen - contains Br or Cl > 900 ppm.
Solder Process Capability	Not applicable for solder process capability

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Compatible Parts





Also in the Series Z-PACK 2mm HM



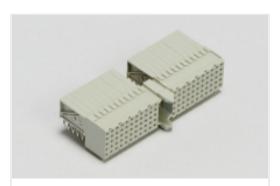
Backplane Connector Housings(4)



Backplane Power Connectors(1)



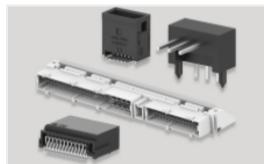
Connector Caps & Covers(62)



Hard Metric Backplane Connectors (266)



Insertion & Extraction Tools(2)



PCB Headers & Receptacles(46)

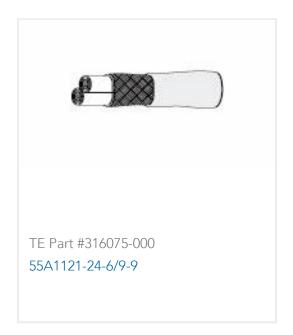


Rectangular Power Connectors(46)

Customers Also Bought





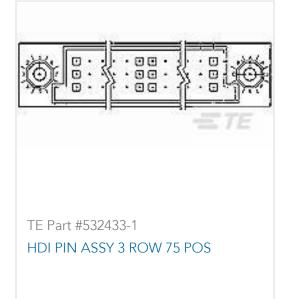








SO96-3-00











Documents

Product Drawings

2MM HM, HEADER, TYPE C

English

CAD Files

3D PDF

3D

Customer View Model

ENG_CVM_CVM_106081-1_C.2d_dxf.zip

English

Customer View Model

ENG_CVM_CVM_106081-1_C.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_106081-1_C.3d_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

Product Specifications

Application Specification

English